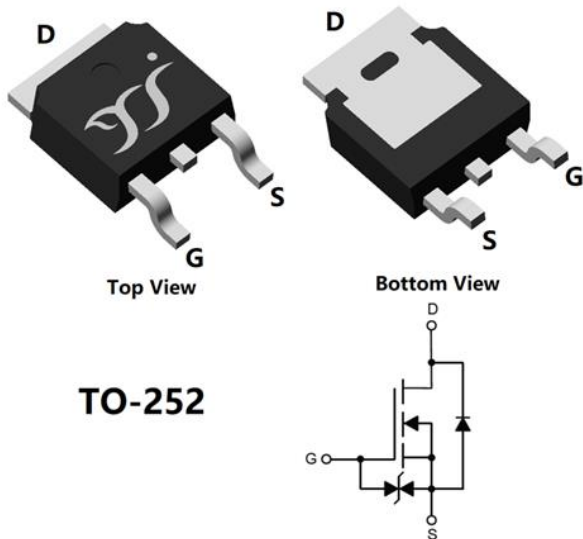


## N-Channel Enhancement Mode Field Effect Transistor



**TO-252**

### Product Summary

- $V_{DS}$  800V
- $I_D$  5.9A
- $R_{DS(ON)}$  (at  $V_{GS}=10V$ ) < 1100m $\Omega$
- 100% EAS Tested
- 100%  $\nabla V_{DS}$  Tested

### General Description

- Excellent package for heat dissipation
- High density cell design for low  $R_{DS(ON)}$
- Epoxy Meets UL 94 V-0 Flammability Rating
- Halogen Free

### Applications

- Power switching application
- Uninterruptible power supply
- DC-DC convertor

### Limiting Values

Parameter	Conditions	Symbol	Min	Max	Unit	
Drain-source Voltage		$V_{DS}$	-	800	V	
Gate-source Voltage		$V_{GS}$	-30	30		
Continuous Drain Current (Note 1,2)	Steady-State	$I_D$	$T_A=25^\circ C, V_{GS}=10V$	-	0.93	A
			$T_A=100^\circ C, V_{GS}=10V$	-	0.58	
Continuous Drain Current (Note 1,3)	Steady-State		$T_C=25^\circ C, V_{GS}=10V, \text{Chip limitation}$	-	5.9	
			$T_C=100^\circ C, V_{GS}=10V$	-	3.7	
Pulsed Drain Current	$T_C=25^\circ C, t_p \leq 10\mu s$	$I_{DM}$	-	13		
Maximum Body-Diode Continuous Current	$T_C=25^\circ C$	$I_S$	-	5.9		
Maximum Body-Diode Pulsed Current	$T_C=25^\circ C, t_p \leq 10\mu s$	$I_{SM}$	-	13		
Avalanche Energy (non-repetitive)	$T_J=25^\circ C, V_G=10V, R_G=25\Omega, L=30mH, I_{AS}=2.6A$	EAS	-	101.4	mJ	
Total Power Dissipation (Note 1,2)	Steady-State	$P_D$	$T_A=25^\circ C$	-	2.5	W
			$T_A=100^\circ C$	-	1	
Total Power Dissipation (Note 1,3)	Steady-State		$T_C=25^\circ C$	-	104	
			$T_C=100^\circ C$	-	41	
MOSFET dv/dt Ruggedness	$V_{DS}=0 \dots 400V, R_G=0\Omega$	dv/dt	-	8	V/ns	
Reverse Diode dv/dt	$V_{DS}=0 \dots 400V, I_D \leq 2A, di/dt=200A/\mu s$	dv/dt	-	7.9		
Maximum Diode Commutation Speed	$V_{DS}=0 \dots 400V, I_D \leq 2A, R_G=0\Omega$	dif/dt	-	629	A/ $\mu s$	
Junction and Storage Temperature Range		$T_J, T_{STG}$	-55	150	$^\circ C$	

### Thermal Resistance

Parameter	Symbol	Typ	Max	Units
Thermal Resistance Junction-to-Ambient (Note 2)	$R_{\theta JA}$	-	49	$^\circ C/W$
Thermal Resistance Junction-to-Case	$R_{\theta JC}$	-	1.2	

### Ordering Information (Example)

PREFERRED P/N	PACKING CODE	Marking	MINIMUM PACKAGE(pcs)	INNER BOX QUANTITY(pcs)	OUTER CARTON QUANTITY(pcs)	DELIVERY MODE
YJD1K1C80BZJ	F2	YJD1K1C80BZ	2500	/	25000	13" reel



# YJD1K1C80BZJ

## ■ Electrical Characteristics

Parameter	Symbol	Conditions	Min	Typ	Max	Units
<b>Static Parameter</b>						
Drain-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS}=0V, I_D=250\mu A, T_j=25^\circ C$	800	-	-	V
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS}=800V, V_{GS}=0V, T_j=25^\circ C$	-	-	1	$\mu A$
		$V_{DS}=800V, V_{GS}=0V, T_j=125^\circ C$	-	-	100	
Gate-Source Leakage Current	$I_{GSS}$	$V_{GS}=\pm 30V, V_{DS}=0V, T_j=25^\circ C$	-	-	$\pm 10$	$\mu A$
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250\mu A, T_j=25^\circ C$	2.5	3.6	4.5	V
Static Drain-Source On-Resistance	$R_{DS(on)}$	$V_{GS}=10V, I_D=3A, T_j=25^\circ C$	-	775	1100	$m\Omega$
		$V_{GS}=10V, I_D=3A, T_j=150^\circ C$	-	2078	2949	$m\Omega$
Diode Forward Voltage	$V_{SD}$	$I_S=5.9A, V_{GS}=0V, T_j=25^\circ C$	-	0.86	1.2	V
Gate Resistance	$R_G$	$f=1MHz, T_j=25^\circ C$	-	34	-	$\Omega$
<b>Dynamic Parameters</b>						
Input Capacitance	$C_{iss}$	$V_{DS}=400V, V_{GS}=0V, f=1MHz, T_j=25^\circ C$	-	583	-	$pF$
Output Capacitance	$C_{oss}$		-	15	-	
Reverse Transfer Capacitance	$C_{rss}$		-	1.2	-	
Effective output capacitance, energy related	$C_{o(er)}$	$V_{DS}=0\dots 400V, V_{GS}=0V, f=1MHz, T_j=25^\circ C$	-	19	-	$pF$
Effective output capacitance, time related	$C_{o(tr)}$		-	70	-	
<b>Switching Parameters</b>						
Total Gate Charge	$Q_g$	$V_{GS}=10V, V_{DS}=400V, I_D=3A, T_j=25^\circ C$	-	14.6	-	$nC$
Gate-Source Charge	$Q_{gs}$		-	3.1	-	
Gate-Drain Charge	$Q_{gd}$		-	6.6	-	
Reverse Recovery Charge	$Q_{rr}$	$I_F=3A, di/dt=100A/\mu s, V_{GS}=0V, V_R=400V, T_j=25^\circ C$	-	1441	-	$nC$
Reverse Recovery Time	$t_{rr}$		-	183	-	ns
Peak Reverse Recovery Current	$I_{rrm}$		-	12.6	-	A
Turn-on Delay Time	$t_{D(on)}$	$V_{GS}=10V, V_{DS}=400V, I_D=3A, R_{GEN}=3\Omega, T_j=25^\circ C$	-	68	-	$ns$
Turn-on Rise Time	$t_r$		-	35	-	
Turn-off Delay Time	$t_{D(off)}$		-	55	-	
Turn-off Fall Time	$t_f$		-	58	-	

### Note:

- The entire application environment impacts the thermal resistance values shown, they are not constants and are only valid for the particular conditions noted.
- The value of  $R_{\theta JA}$  is measured with the device mounted on the 40mm\*40mm\*1.1mm single layer FR-4 PCB board with 1 in<sup>2</sup> pad of 2oz. Copper, in the still air environment with  $T_A=25^\circ C$ . The maximum allowed junction temperature of 150 $^\circ C$ . The value in any given application depends on the user's specific board design.
- Thermal resistance from junction to soldering point (on the exposed drain pad).



# YJD1K1C80BZJ

## Typical Electrical and Thermal Characteristics Diagrams

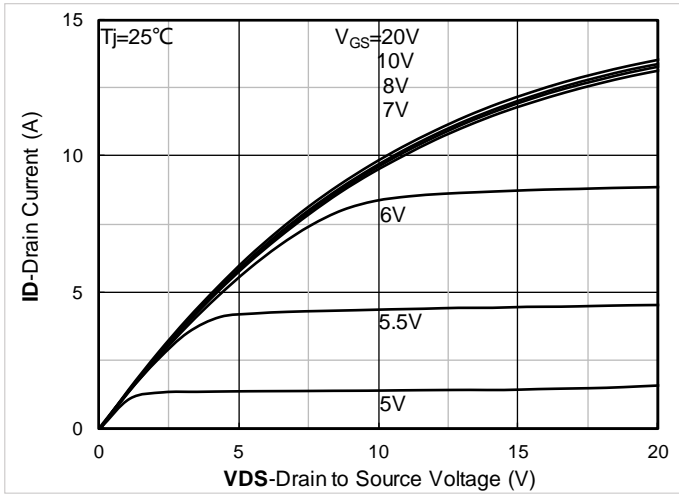


Figure 1. Output Characteristics; typical values

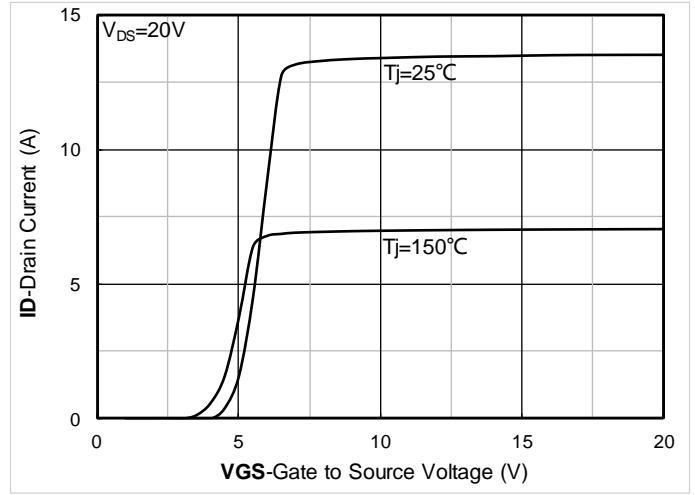


Figure 2. Transfer Characteristics; typical values

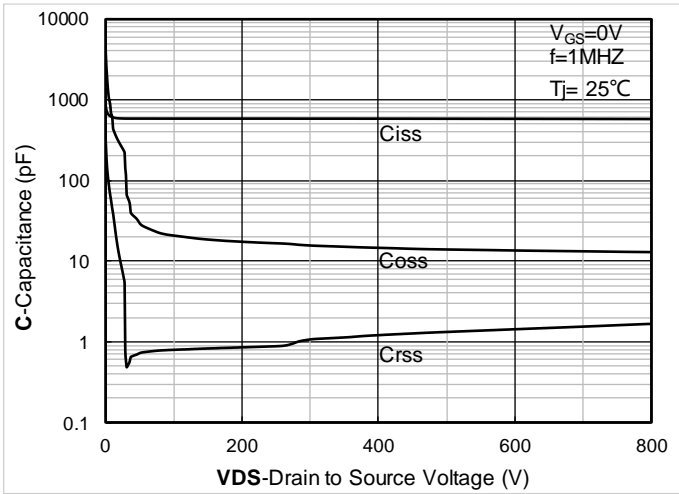


Figure 3. Capacitance Characteristics; typical values

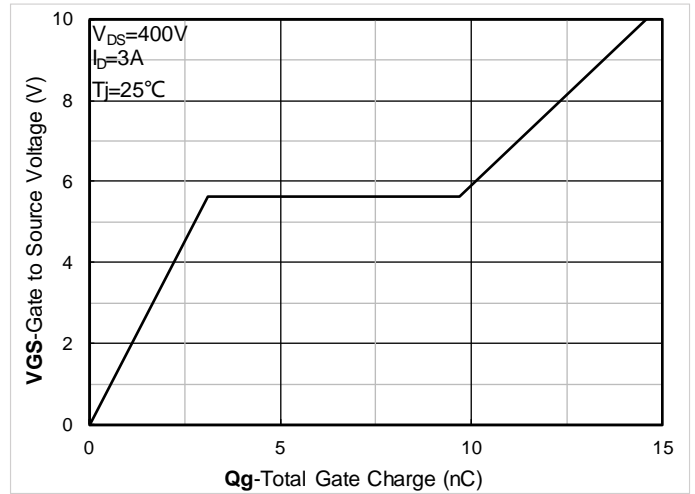


Figure 4. Gate Charge; typical values

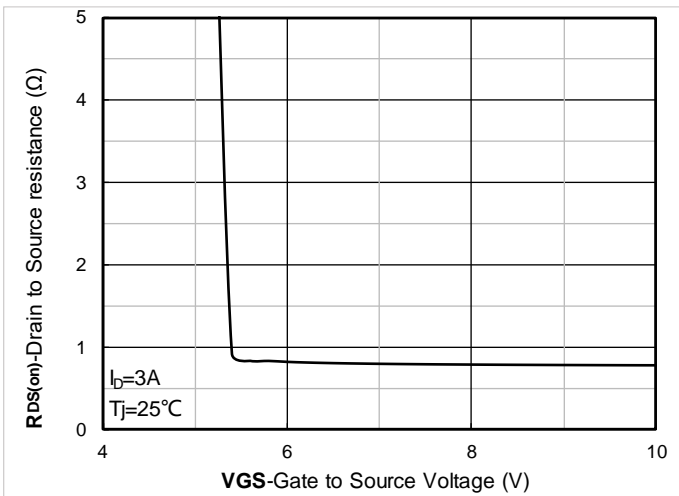


Figure 5. On-Resistance vs. Gate to Source Voltage; typical values

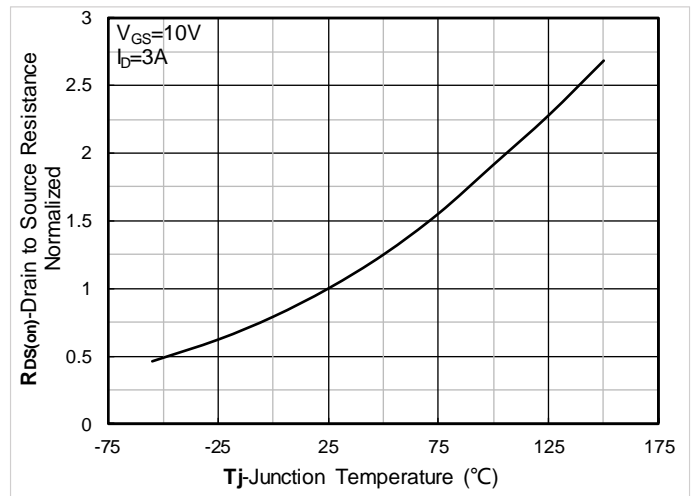


Figure 6. Normalized On-Resistance



# YJD1K1C80BZJ

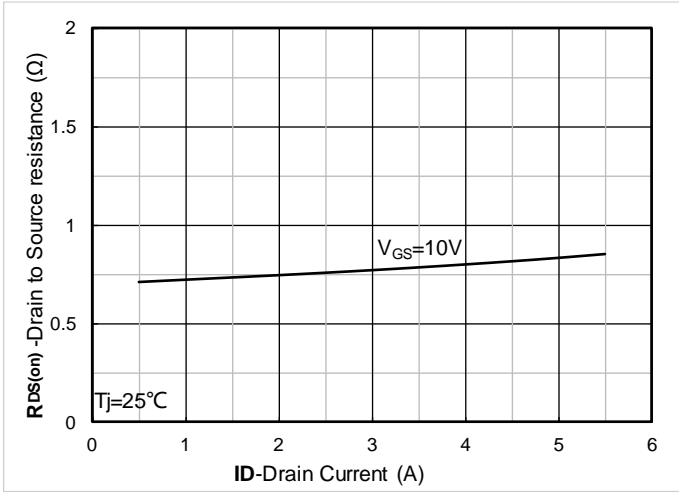


Figure 7. RDS(on) vs. Drain Current; typical values

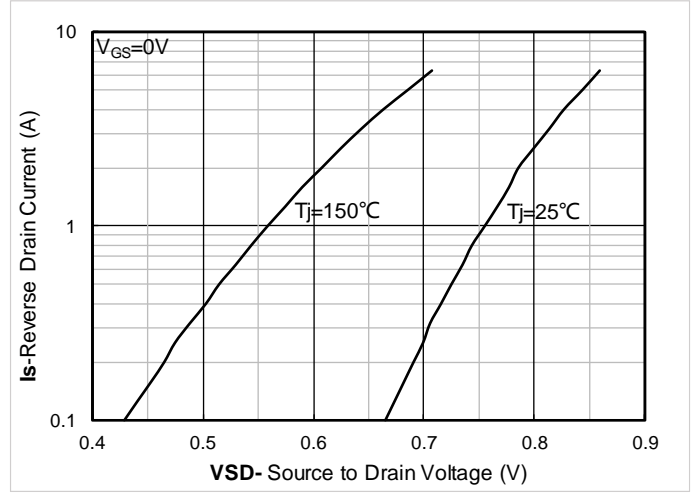


Figure 8. Forward characteristics of reverse diode; typical values

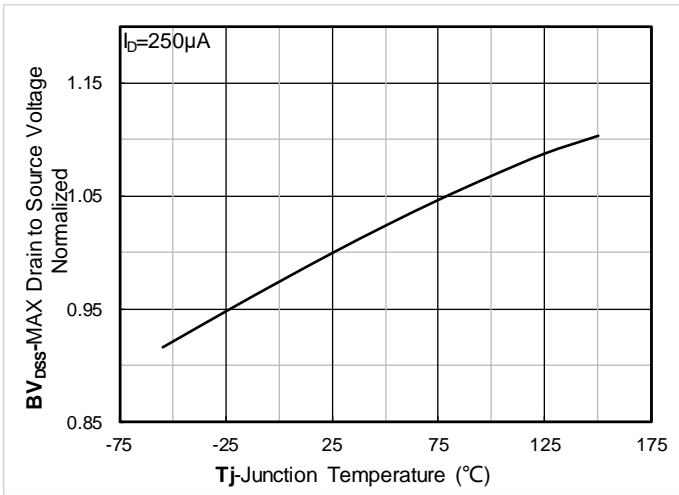


Figure 9. Normalized breakdown voltage

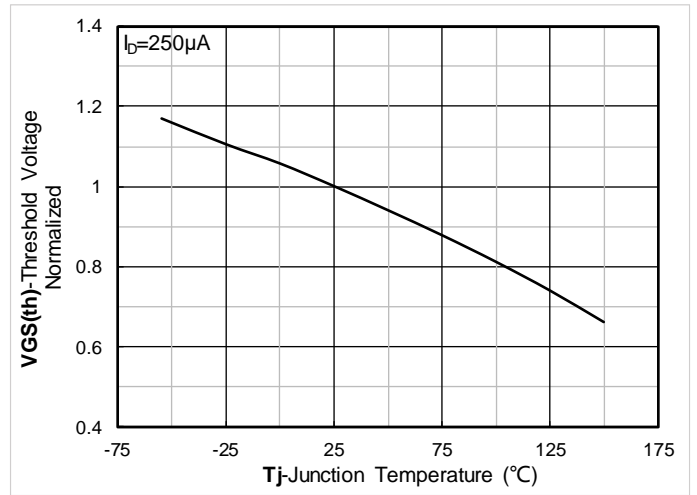


Figure 10. Normalized Threshold voltage

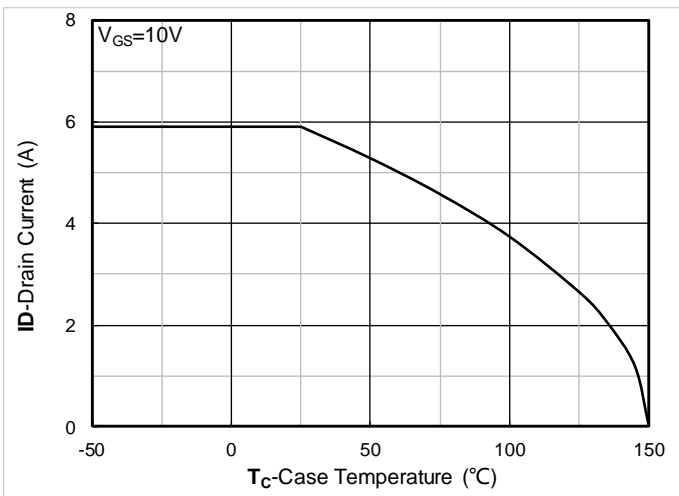


Figure 11. Current dissipation

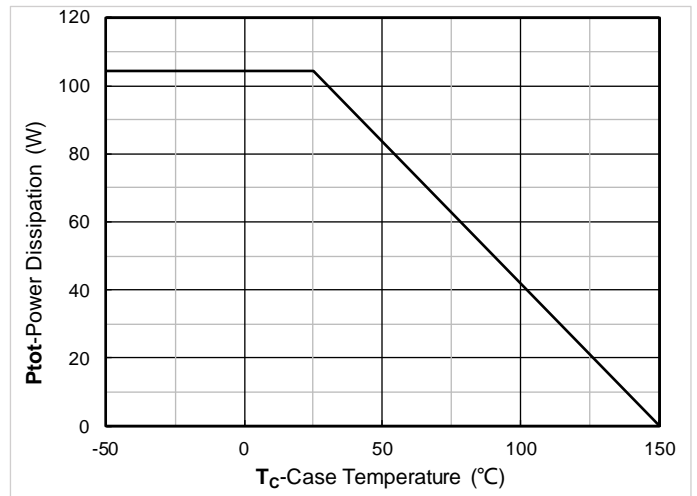


Figure 12. Power dissipation



# YJD1K1C80BZJ

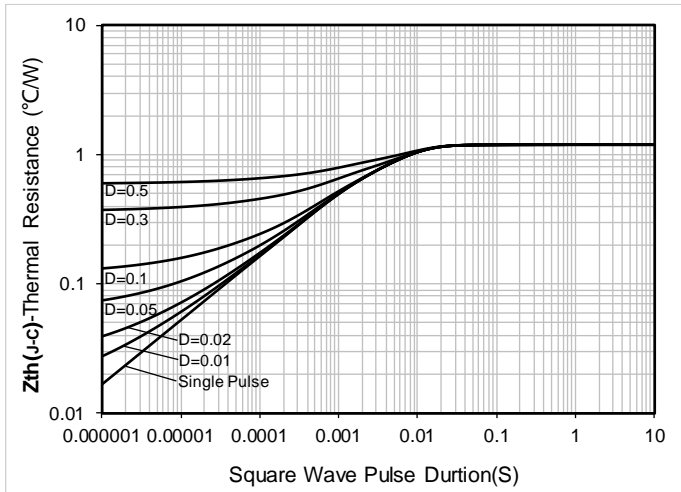


Figure 13. Maximum Transient Thermal Impedance

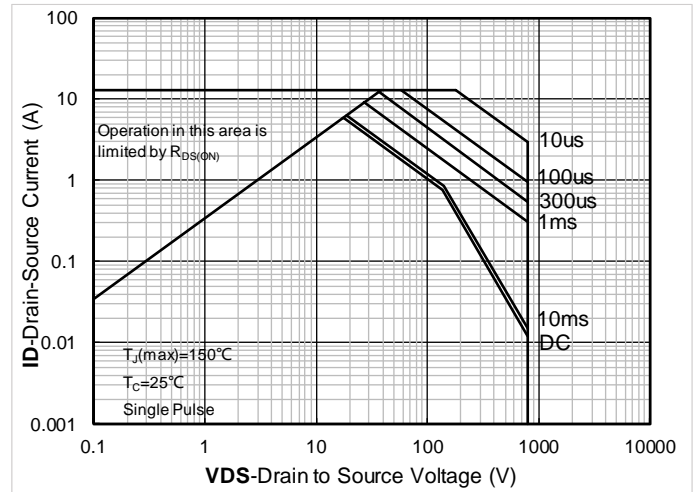


Figure 14. Safe Operation Area

## ■ Test Circuits & Waveforms

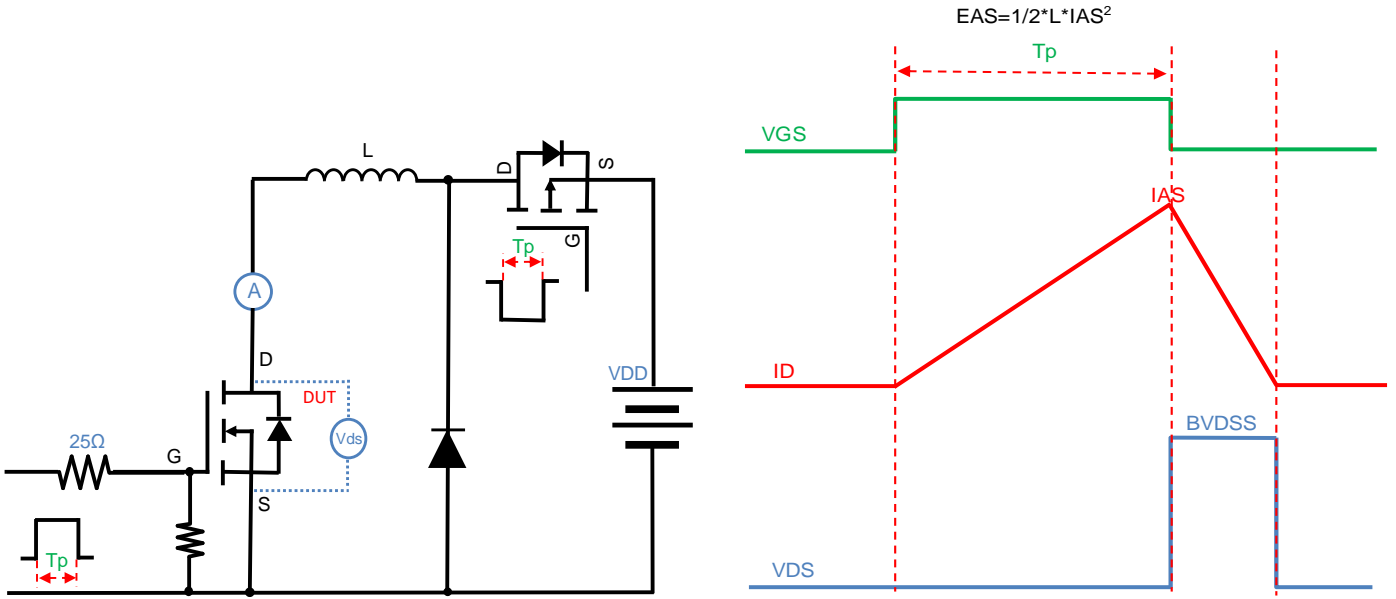


Figure A. Unclamped Inductive Switching (UIS) Test Circuit & Waveform

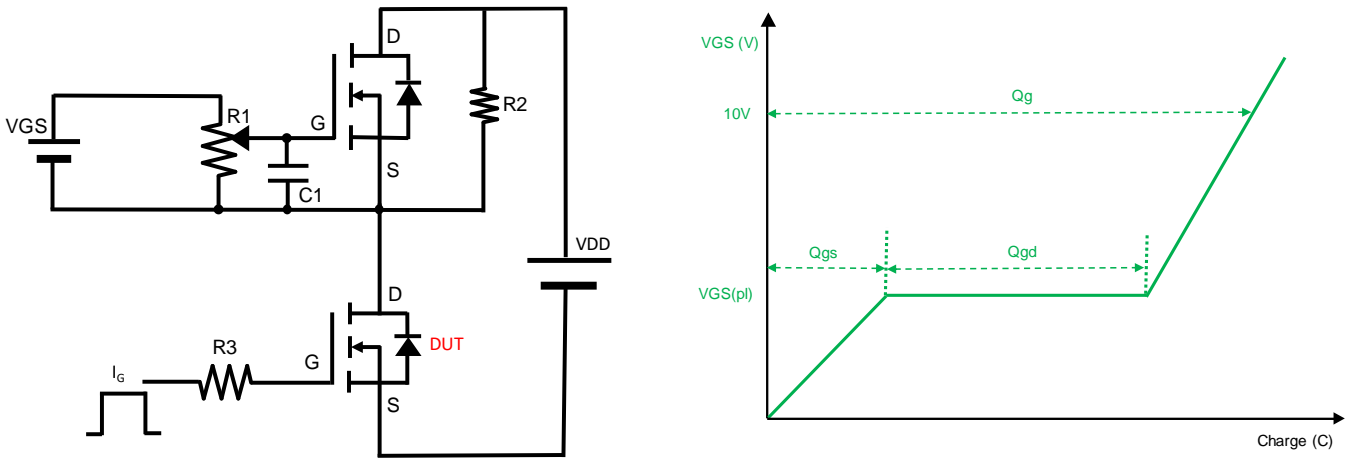


Figure B. Gate Charge Test Circuit & Waveform

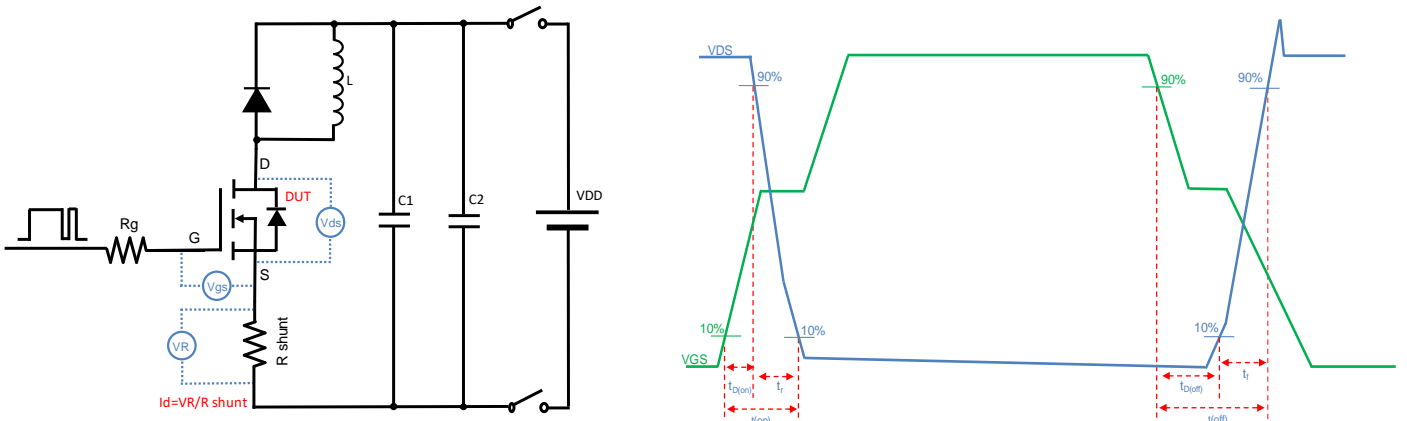


Figure C. Resistive Switching Test Circuit & Waveform

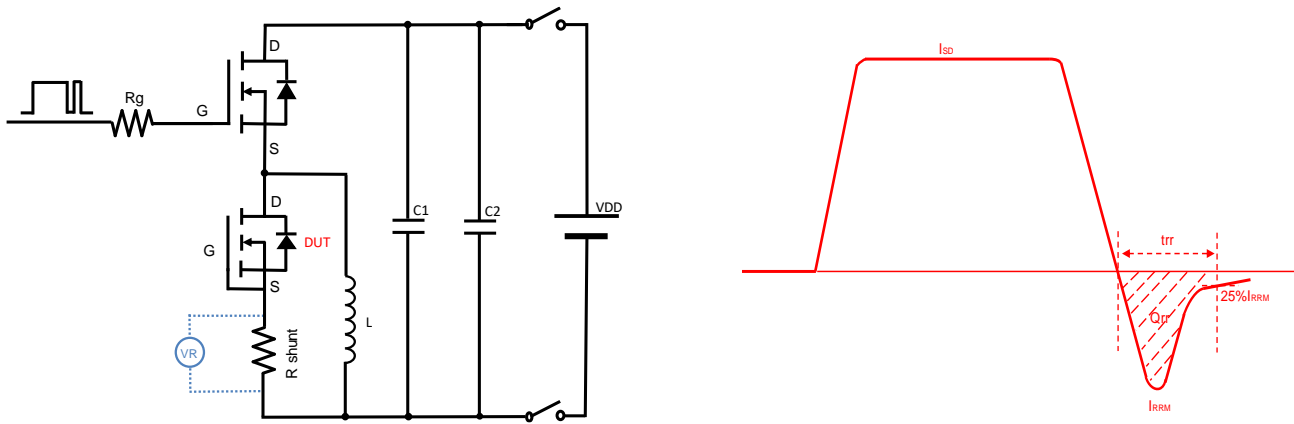
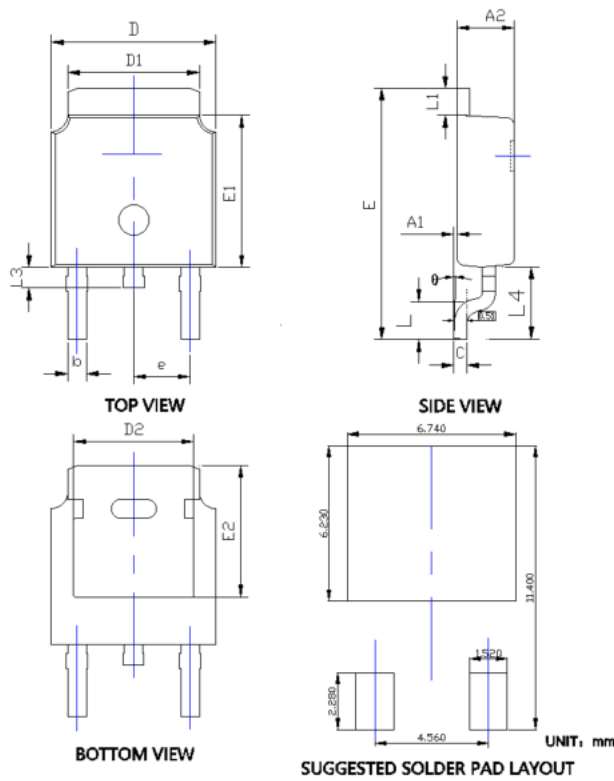


Figure D. Diode Recovery Test Circuit & Waveform



# YJD1K1C80BZJ

## ■ TO-252-C Package information



SYMBOL	DIMENSIONS			
	INCHES		Millimeter	
	MIN.	MAX.	MIN.	MAX.
A1	0.000	0.008	0.000	0.200
A2	0.086	0.094	2.180	2.400
b	0.026	0.035	0.660	0.890
c	0.018	0.024	0.460	0.610
D	0.250	0.265	6.350	6.730
D1	0.195	0.215	4.950	5.460
D2	0.170	-	4.320	-
E	0.370	0.410	9.400	10.410
E1	0.235	0.245	5.970	6.220
E2	0.203	-	5.150	-
e	0.090	REF	2.286	REF
L	0.049	0.070	1.250	1.780
L1	0.035	0.050	0.890	1.270
L3	0.024	0.039	0.600	1.000
L4	0.102	0.126	2.600	3.200
θ	0°	10°	0°	10°

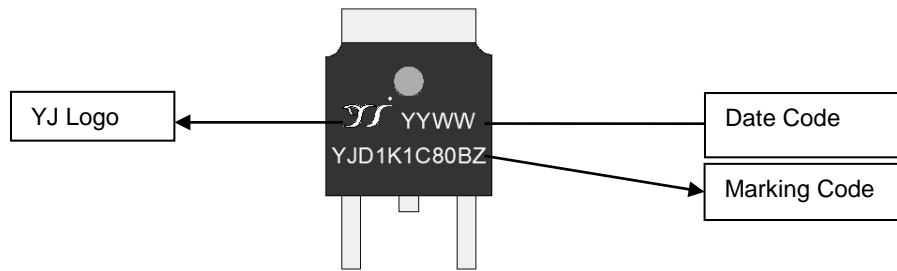
**NOTE:**  
 1. PACKAGE BODY SIZES EXCLUDE MOLD FLASH AND GATE BURRS.  
 2. TOLERANCE 0.1mm UNLESS OTHERWISE SPECIFIED.  
 3. THE PAD LAYOUT IS FOR REFERENCE PURPOSES ONLY.





# YJD1K1C80BZJ

## ■ Marking Information



**Note:**

1. All marking is at middle of the product body
2. All marking is in laser printing
3. YJD1K1C80BZ is marking code, YYWW is date code, "YY" is year, "WW" is week
4. Body color: Black



## YJD1K1C80BZJ

---

### Disclaimer

The information presented in this document is for reference only. Yangzhou Yangjie Electronic Technology Co., Ltd. reserves the right to make changes without notice for the specification of the products displayed herein to improve reliability, function or design or otherwise.

The product listed herein is designed to be used with ordinary electronic equipment or devices, and not designed to be used with equipment or devices which require high level of reliability and the malfunction of which would directly endanger human life (such as medical instruments, transportation equipment, aerospace machinery, nuclear-reactor controllers, fuel controllers and other safety devices), Yangjie or anyone on its behalf, assumes no responsibility or liability for any damages resulting from such improper use of sale.

This publication supersedes & replaces all information previously supplied. For additional information, please visit our website <http://www.21yangjie.com> , or consult your nearest Yangjie's sales office for further assistance.